

Title (en)

Apparatus and method for depositing a substance with temperature control

Title (de)

Vorrichtung und Methode mit Temperaturreglung zum Abscheiden eines Werkstoffes

Title (fr)

Appareillage et méthode avec régulation de température pour la déposition d'un matériau

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EP 0747505 A2 19961211 (EN)

Application

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Abstract (en)

A method and corresponding apparatus for depositing a substance with temperature control on a surface of a substrate are disclosed. The method comprises the steps of : providing a cooling block having a surface that is cooled by heat exchange ; supporting said substrate from said cooling block so that the bottom surface of said substrate is spaced from said cooling block surface by a gap ; providing a gas in said gap ; and depositing said substance on the top surface of said substrate. With such a method, the temperature conditions are uniform and repeatable when depositing a substance on a substrate. The invention is especially applicable to deposition of diamond by plasma jet. <IMAGE>

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